

Sub 17  
attaching an interposer to a package substrate;

attaching an integrated circuit die to the interposer, wherein the integrated circuit die includes an active region;

covering the package substrate, the integrated circuit die, and the interposer with a heat spreader to form an internal chamber;

filling the internal chamber with a cooling fluid, wherein the cooling fluid contacts a region between the interposer and the integrated circuit die and wherein the cooling fluid contacts the active region.

Sub 17  
B2  
17. (Amended) An integrated circuit package comprising:

a package substrate;

a first integrated circuit die having an active surface;

an interposer disposed between the package substrate and the first integrated circuit die, the interposer establishing electrical connectivity between the first integrated circuit die and the package substrate; and

a cooling fluid disposed between the first integrated circuit die and the interposer, wherein the cooling fluid contacts the active surface.